

Product Change Notification - GBNG-31RCYV061

Date:

20 Apr 2020

Product Category:

OTN Processors & PHYs

Affected CPNs:

Notification subject:

CCB 3744 Final Notice: Qualification of ASE as a new bumping facility and assembly site for selected Microsemi products available in 1932L BBGA (45x45x4.0mm) package.

Notification text:
PCN Status:

Final notification.

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new bumping facility and assembly site for selected Microsemi products available in 1932L BBGA (45x45x4.0mm) package.

Pre Change:

Assembled at ATK site and bumping facility at ATT using NAU-27-1F underfill material

Post Change:

Assembled and bumping facility at ASE site using UA59 underfill material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Technology Korea (K4), INC. (ATK)	ASE Inc. (ASE)
Bumping facility	Amkor Technology Taiwan (ATT)	
Bump material	SnAg	SnAg
Underfill material	NAU-27-1F	UA59

Impacts to Data Sheet:

None



Change Impact:

None

Reason for Change:

To improve on time delivery performance by qualifying ASE as a new bumping facility and assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 20, 2020 (date code: 2021)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	May 2019					-->	April 2020					-->	May 2020				
	31	32	33	34	35		14	15	16	17	18		19	20	21	22	
Initial PCN Issue Date				X													
Qual Report Availability										X							
Final PCN Issue Date										X							
Estimated Implementation Date														X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 03, 2019: Issued initial notification.

March 9, 2020: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on April 9, 2020.

April 20, 2020: Re-issued final notification. Updated the qualification report removing "Digi-G4" from the device no. field in the qual report. Updated estimated first ship date to be on May 20, 2020 and updated the time-table summary.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN GBNG-31RCYV061 Qual Report Rev 1.pdf](#)



Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PM5993B-FEI
PM5992B-FEI
PM5991B-FEI
PM5990B-FEI
PM5985B-FEI
PM5984B-FEI
PM5981B-FEI
PM5980B-FEI
PM5998B-FEI
PM5997B-FEI
PM5986A-FEI
PM5991B-FEI-PD